



Final Product Change Notification

201810026F01

Issue Date: 20-Dec-2018

Effective Date: 19-Mar-2019

Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Management Summary

Cu Wire is being added as a wirebond material option for LPC18xx, LPC18x0, LPC43xx and LPC43x0 in LQFP packages at assembly site NXP-ATKH.

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

LPC18xx, LPC43xx LQFP
Package Cu Wire
Qualification for NXP-
ATKH

Description of Change

Copper wire has been qualified and will be added as a wirebond material. Upon effective date, NXP will begin shipping product with copper wire.

See attached Self Qualification Reports (SQR) for details of the affected part numbers, material changes and qualification test results.

Samples of the following superset part numbers will be available.

LPC4357JBD208, LPC4337JBD144, LPC4330FBD144,
LPC1857JBD208, LPC1837JBD144, LPC1830FBD144,
LPC1820FBD144/3D, LPC1820FBD144,
LPC43S20BD144/CP3332

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-08

Reason for Change

Adding Copper wire is required to mitigate against raw material cost increases and for supply assurance.

Identification of Affected Products

Top side marking

Product version is incremented. See marking details in attached Self Qualification Report (SQR) document.

Product Availability

Sample Information

Samples are available from 31-Dec-2018

Sample requests can be sent to the email address below in Contact and Support.

Production

Planned first shipment 20-Mar-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

Wire composition is the only change. No Impact to form, fit or function. Reliability is equivalent or improved.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 19-Jan-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind
Position Senior Quality Engineer
e-mail address tim.camenzind@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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